



Material Content Data Sheet



Sales Product Name		TLE4963-1M		Issued		24. August 2015		
MA#		MA001395414						
Package		PG-SOT23-3-15		Weight*		9.78 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.220	2.25	2.25	22458	22458
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		74	
	non noble metal	titanium	7440-32-6	0.004	0.04		369	
	non noble metal	chromium	7440-47-3	0.011	0.11		1106	
wire	non noble metal	copper	7440-50-8	3.590	36.71	36.87	367146	368695
	noble metal	gold	7440-57-5	0.023	0.24	0.24	2360	2360
	encapsulation	organic material	carbon black	1333-86-4	0.055	0.56		5618
encapsulation	plastics	epoxy resin	-	1.181	12.08		120790	
	inorganic material	silicondioxide	60676-86-0	4.257	43.54	56.18	435405	561813
leadfinish	non noble metal	tin	7440-31-5	0.152	1.55	1.55	15496	15496
plating	noble metal	silver	7440-22-4	0.149	1.52	1.52	15197	15197
glue	plastics	epoxy resin	-	0.024	0.24		2447	
	noble metal	silver	7440-22-4	0.113	1.15	1.39	11534	13981
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com